

The logo for TMS 2017 features the letters 'TMS' in a large, bold, blue font with a white outline, followed by '2017' in a smaller, solid blue font. The logo is set against a circular background with a light blue and white geometric pattern.

# TMS 2017

# PROFESSIONAL DEVELOPMENT

February 26 – March 2, 2017 • San Diego, California, USA

**BROADEN YOUR EXPERTISE:**

**REGISTER FOR A PROFESSIONAL DEVELOPMENT EVENT AT TMS2017**

## **EMERGING ELECTRONIC INTERCONNECT MATERIALS AND PROCESSING FOR ADVANCED PACKAGING TECHNOLOGY WORKSHOP**

**SUNDAY, FEBRUARY 26, 2017 • 8:30 A.M. TO 4:30 P.M.**

### **Organizers**

**Andre Lee**, Michigan State University, (Lead Organizer); **Iver Anderson**, Iowa State University and Ames National Laboratory; **Srinivas Chada**, Stryker; **Fu Guo**, Beijing University of Technology; and **Carol Handwerker**, Purdue University

### **Workshop Overview**

This workshop will focus on developing the fundamentals of materials science and engineering strategies of electronic interconnect materials/systems to meet the high performance and the high reliability demanded on electronics. Modern electronics must be multi-functional and highly connected, so the materials used and manufacturing of electronic devices need to be sustainable. Materials and strategies employed to connect different levels in electronic packages play a critical role. This workshop will introduce current trends, technological aspects from different industries, and key research findings from both industry and academia.

### **Registration Fees**

Register for this professional development event through the TMS 2017 Annual Meeting & Exhibition Registration Form.

	<b>Through January 20, 2017</b>	<b>After January 20, 2017</b>
<b>Member</b>	\$45	\$95
<b>Nonmember</b>	\$145	\$195
<b>Student</b>	\$25	\$95

The TMS logo consists of the letters 'TMS' in a large, bold, red font with a white outline.

# TMS

Sponsored by the Functional Materials Division and  
TMS Professional Development Committee.

This workshop builds upon the Lead-Free Solders and Interconnect  
Technology Workshop held at past TMS Annual Meetings.

**Learn more at: [www.tms.org/TMS2017/Interconnect](http://www.tms.org/TMS2017/Interconnect)**